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$V_{DSS}$	1200V
$R_{DS(on)}$ (Typ.)	160mΩ
$I_D$	22A
$P_D$	165W

### ●Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Fast reverse recovery
- 4) Easy to parallel
- 5) Simple to drive
- 6) Pb-free lead plating ; RoHS compliant

### ●Application

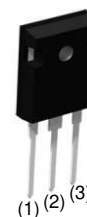
- Solar inverters
- DC/DC converters
- Switch mode power supplies
- Induction heating
- Motor drives

### ●Absolute maximum ratings ( $T_a = 25^\circ\text{C}$ )

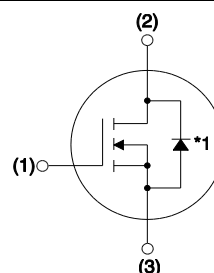
Parameter		Symbol	Value	Unit
Drain - Source voltage		$V_{DSS}$	1200	V
Continuous drain current	$T_c = 25^\circ\text{C}$	$I_D^{*1}$	22	A
	$T_c = 100^\circ\text{C}$	$I_D^{*1}$	16	A
Pulsed drain current		$I_{D,pulse}^{*2}$	55	A
Gate - Source voltage (DC)		$V_{GSS}$	-6 to 22	V
Gate - Source surge voltage ( $T_{surge} < 300\text{nsec}$ )		$V_{GSS-surge}^{*3}$	-10 to 26	V
Power dissipation ( $T_c = 25^\circ\text{C}$ )		$P_D$	165	W
Junction temperature		$T_j$	175	$^\circ\text{C}$
Range of storage temperature		$T_{stg}$	-55 to +175	$^\circ\text{C}$

### ●Outline

TO-247



### ●Inner circuit



(1) Gate  
(2) Drain  
(3) Source

\*1 Body Diode

### ●Packaging specifications

Type	Packaging	Tube
	Reel size (mm)	-
	Tape width (mm)	-
	Basic ordering unit (pcs)	30
	Packing code	C
	Marking	SCT2160KE

### ●Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal resistance, junction - case	$R_{thJC}$	-	0.70	0.91	°C/W
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	50	°C/W
Soldering temperature, wavesoldering for 10s	$T_{sold}$	-	-	265	°C

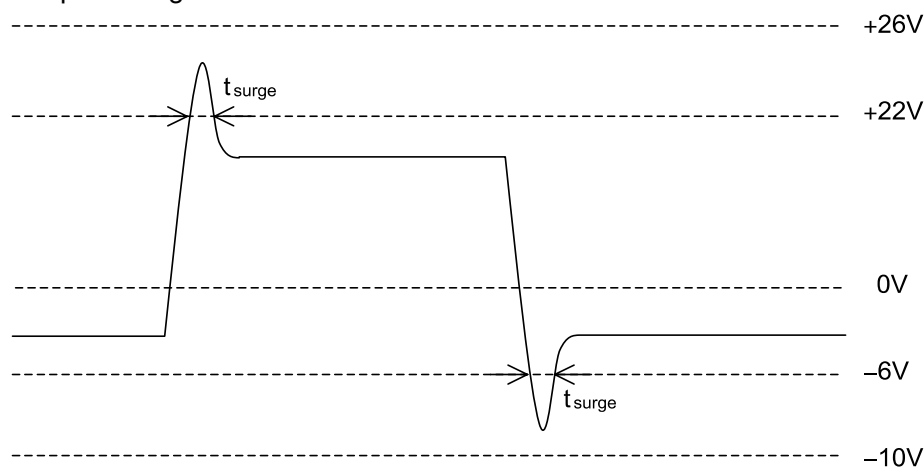
### ●Electrical characteristics ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 1mA$	1200	-	-	V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 1200V, V_{GS} = 0V$ $T_j = 25^\circ\text{C}$	-	1	10	$\mu\text{A}$
		$T_j = 150^\circ\text{C}$	-	2	-	
Gate - Source leakage current	$I_{GSS+}$	$V_{GS} = +22V, V_{DS} = 0V$	-	-	100	nA
Gate - Source leakage current	$I_{GSS-}$	$V_{GS} = -6V, V_{DS} = 0V$	-	-	-100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 2.5mA$	1.6	2.8	4.0	V

\*1 Limited only by maximum temperature allowed.

\*2  $PW \leq 10\mu\text{s}$ , Duty cycle  $\leq 1\%$

\*3 Example of acceptable Vgs waveform



\*4 Pulsed

**●Electrical characteristics** ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Static drain - source on - state resistance	$R_{DS(on)}^{*4}$	$V_{GS} = 18\text{V}, I_D = 7\text{A}$ $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	- -	160 226	208 -	$\text{m}\Omega$
Gate input resistance	$R_G$	$f = 1\text{MHz}$ , open drain	-	13.7	-	$\Omega$
Transconductance	$g_{fs}^{*4}$	$V_{DS} = 10\text{V}, I_D = 7\text{A}$	-	2.4	-	S
Input capacitance	$C_{iss}$	$V_{GS} = 0\text{V}$	-	1200	-	pF
Output capacitance	$C_{oss}$	$V_{DS} = 800\text{V}$	-	45	-	
Reverse transfer capacitance	$C_{rss}$	$f = 1\text{MHz}$	-	7	-	
Effective output capacitance, energy related	$C_{o(er)}$	$V_{GS} = 0\text{V}$ $V_{DS} = 0\text{V to } 500\text{V}$	-	71	-	pF
Turn - on delay time	$t_{d(on)}^{*4}$	$V_{DD} = 400\text{V}, I_D = 7\text{A}$	-	23	-	ns
Rise time	$t_r^{*4}$	$V_{GS} = 18\text{V}/0\text{V}$	-	25	-	
Turn - off delay time	$t_{d(off)}^{*4}$	$R_L = 57\Omega$	-	67	-	
Fall time	$t_f^{*4}$	$R_G = 0\Omega$	-	27	-	
Turn - on switching loss	$E_{on}^{*4}$	$V_{DD} = 600\text{V}, I_D = 7\text{A}$ $V_{GS} = 18\text{V}/0\text{V}$ $R_G = 0\Omega, L = 500\mu\text{H}$	-	126	-	$\mu\text{J}$
Turn - off switching loss	$E_{off}^{*4}$	* $E_{on}$ includes diode reverse recovery	-	55	-	

**●Gate Charge characteristics** ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Total gate charge	$Q_g^{*4}$	$V_{DD} = 400\text{V}$	-	62	-	nC
Gate - Source charge	$Q_{gs}^{*4}$	$I_D = 7\text{A}$	-	14	-	
Gate - Drain charge	$Q_{gd}^{*4}$	$V_{GS} = 18\text{V}$	-	20	-	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} = 400\text{V}, I_D = 7\text{A}$	-	9.6	-	V



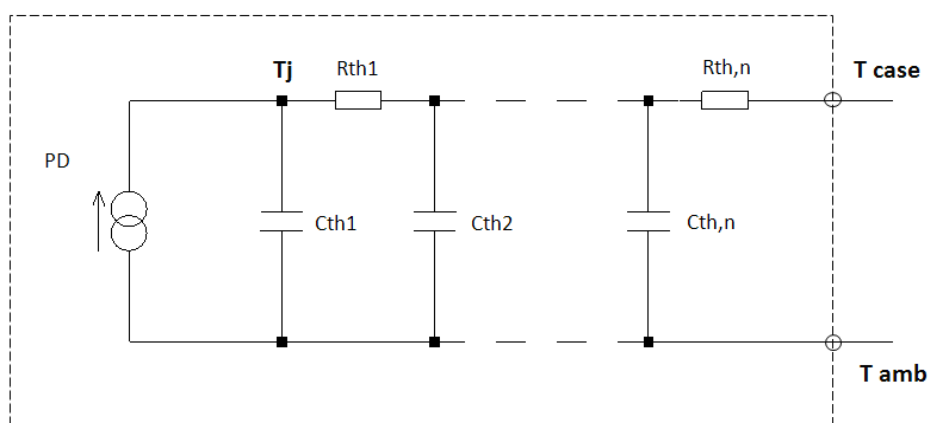
**●Body diode electrical characteristics (Source-Drain) ( $T_a = 25^\circ\text{C}$ )**

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Inverse diode continuous, forward current	$I_S^{*1}$	$T_c = 25^\circ\text{C}$	-	-	22	A
Inverse diode direct current, pulsed	$I_{SM}^{*2}$		-	-	55	A
Forward voltage	$V_{SD}^{*4}$	$V_{GS} = 0\text{V}, I_S = 7\text{A}$	-	4.1	-	V
Reverse recovery time	$t_{rr}^{*4}$	$I_F = 7\text{A}, V_R = 400\text{V}$ $di/dt = 160\text{A}/\mu\text{s}$	-	26	-	ns
Reverse recovery charge	$Q_{rr}^{*4}$		-	39	-	nC
Peak reverse recovery current	$I_{rrm}^{*4}$		-	3.0	-	A

**●Typical Transient Thermal Characteristics**

Symbol	Value	Unit
$R_{th1}$	96.1m	K/W
$R_{th2}$	404m	
$R_{th3}$	196m	

Symbol	Value	Unit
$C_{th1}$	1.55m	Ws/K
$C_{th2}$	5.23m	
$C_{th3}$	83.3m	



●Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

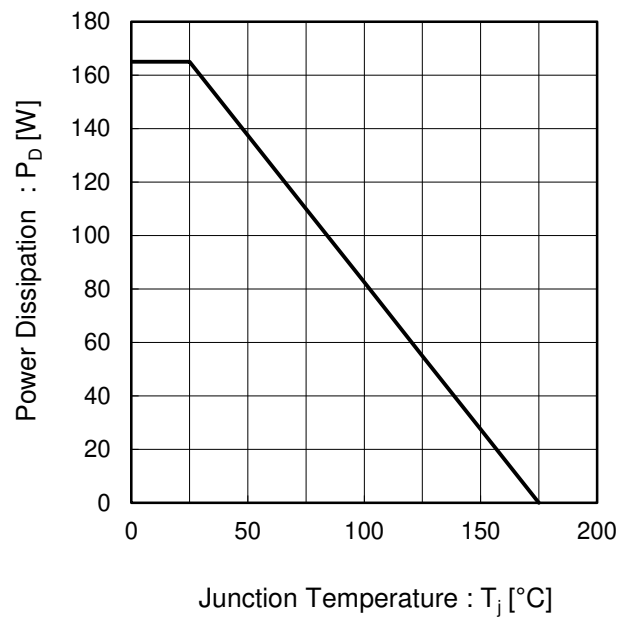


Fig.2 Maximum Safe Operating Area

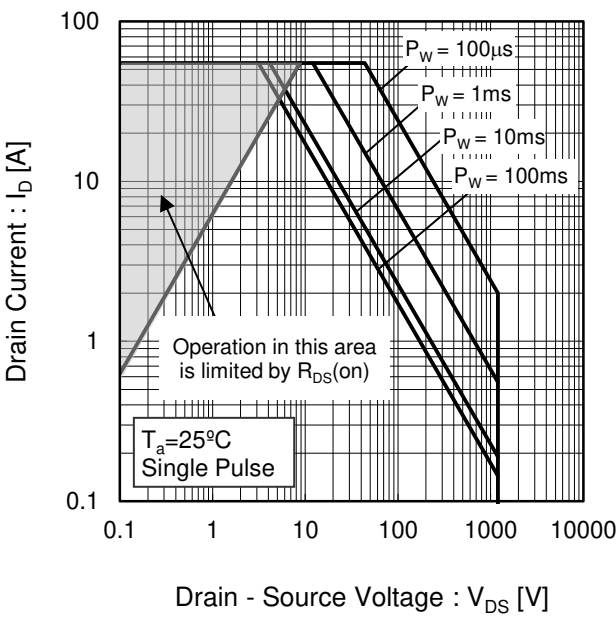
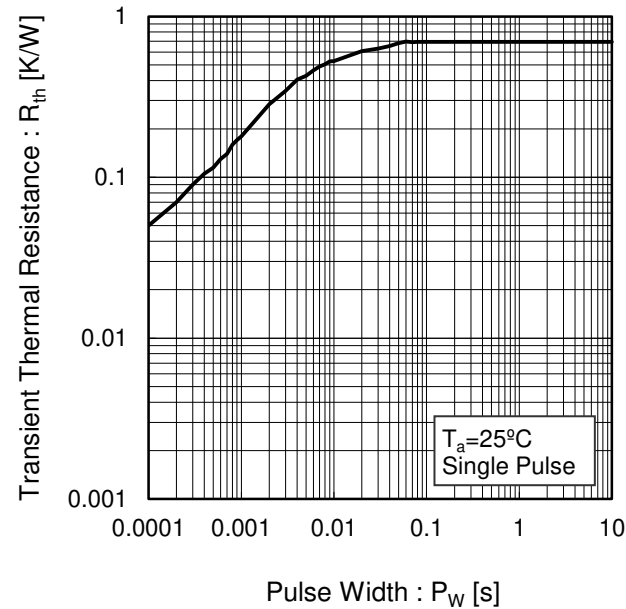


Fig.3 Typical Transient Thermal Resistance vs. Pulse Width





●Electrical characteristic curves

Fig.8 Typical Transfer Characteristics (I)

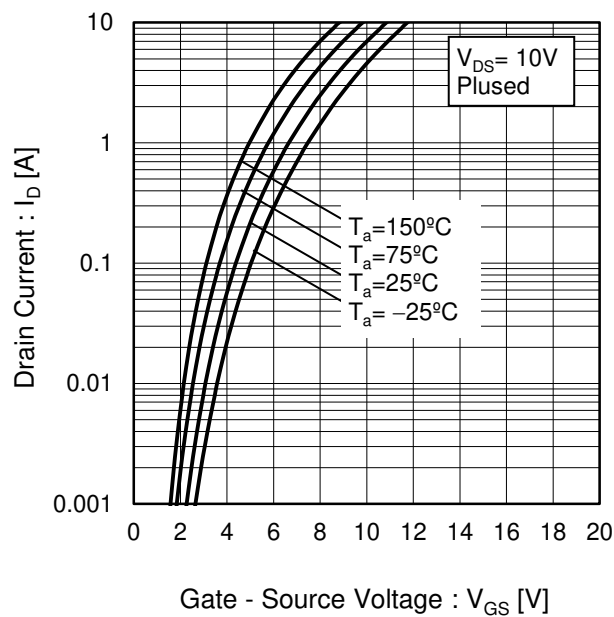


Fig.9 Typical Transfer Characteristics (II)

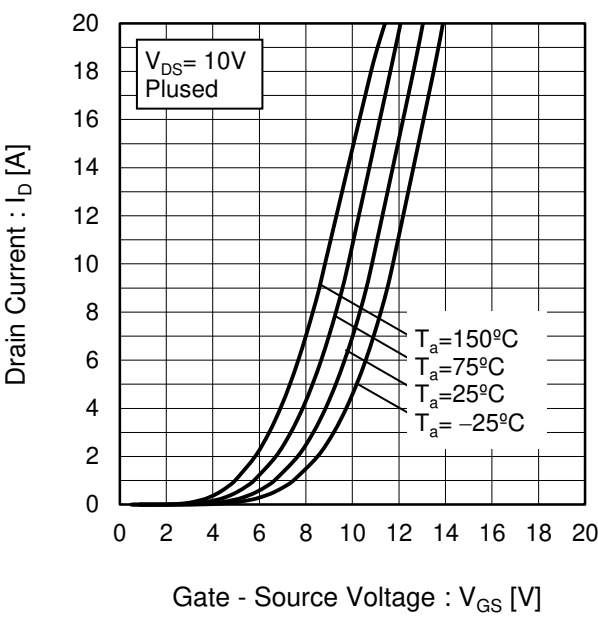


Fig.10 Gate Threshold Voltage vs. Junction Temperature

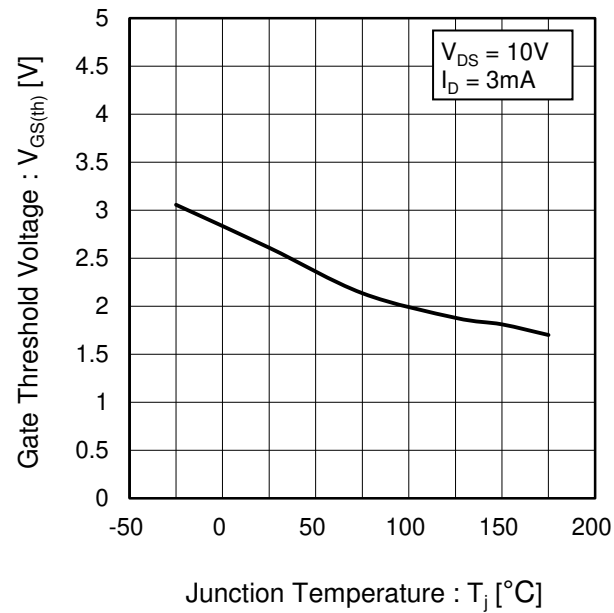
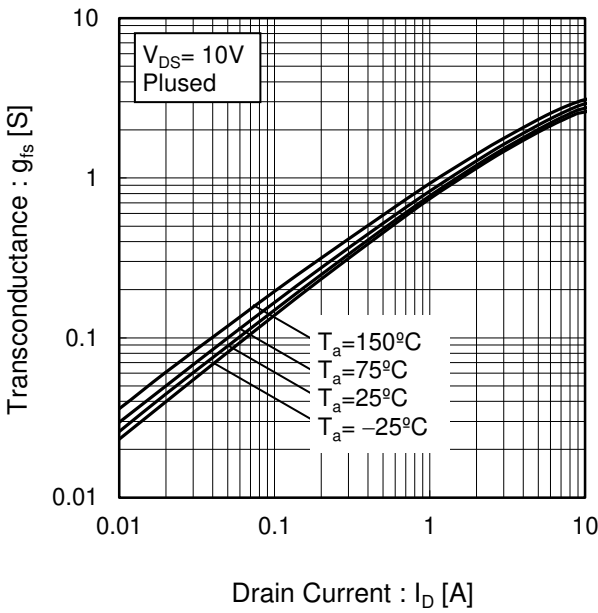


Fig.11 Transconductance vs. Drain Current





●Electrical characteristic curves

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

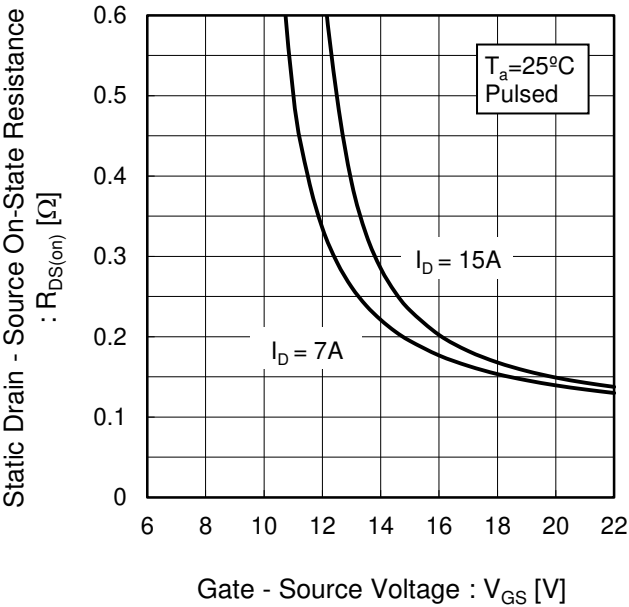


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

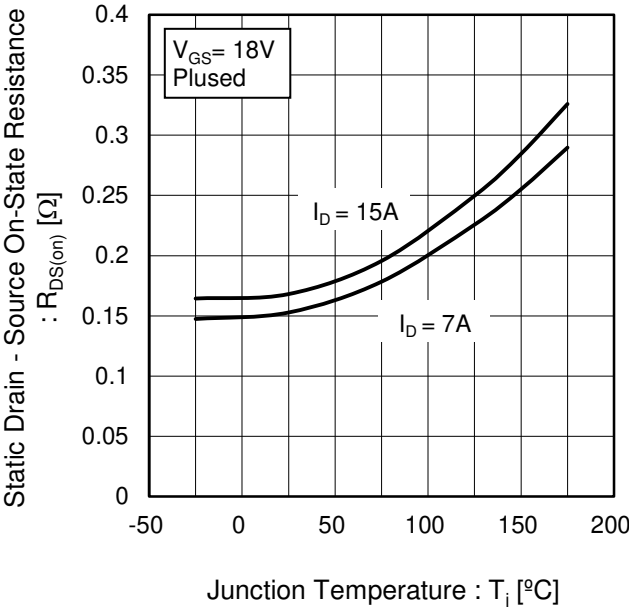
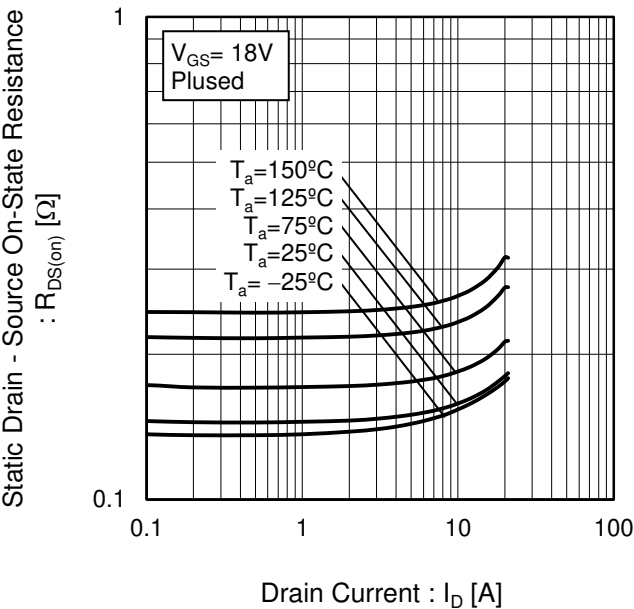


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current



●Electrical characteristic curves

Fig.15 Typical Capacitance vs. Drain - Source Voltage

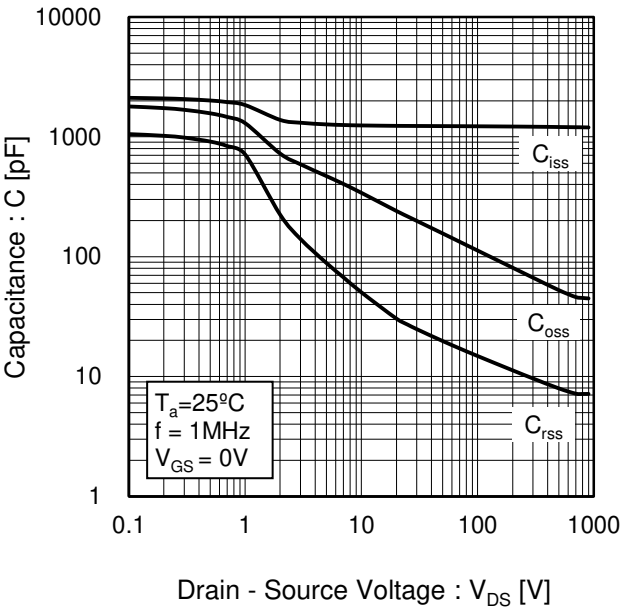


Fig.16 Coss Stored Energy

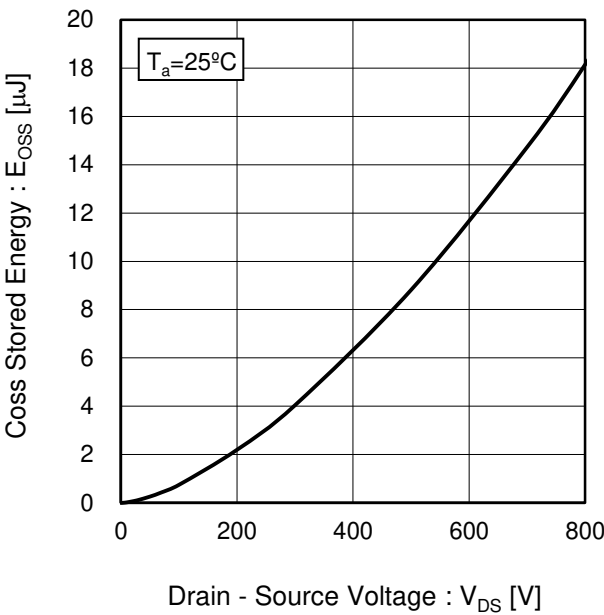


Fig.17 Switching Characteristics

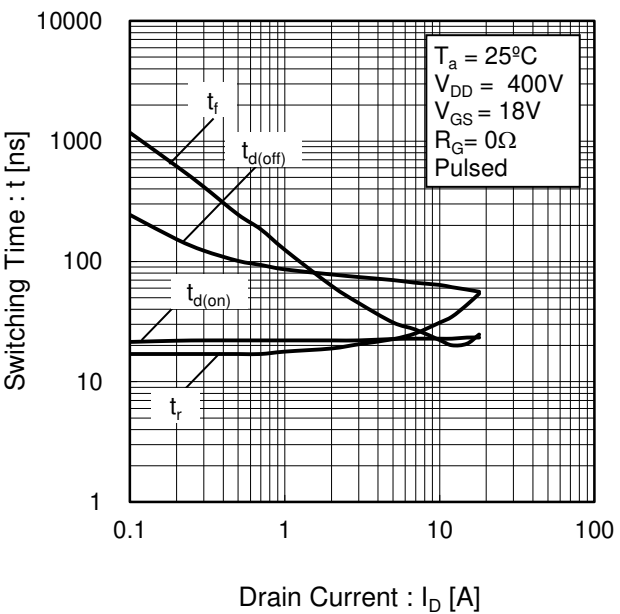
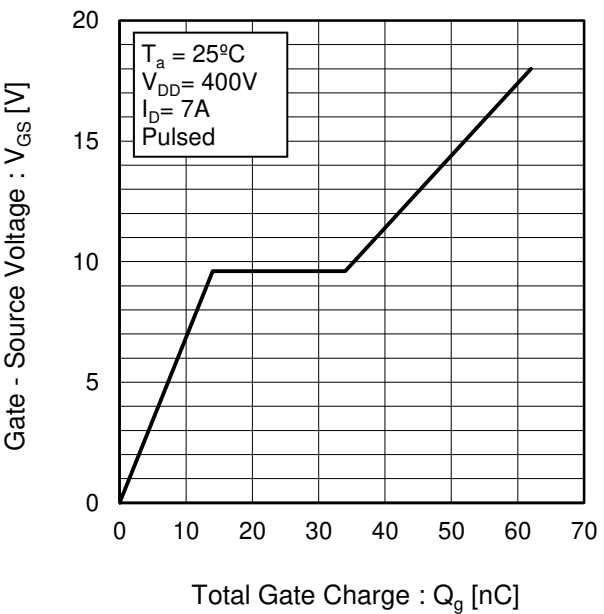


Fig.18 Dynamic Input Characteristics



●Electrical characteristic curves

Fig.19 Typical Switching Loss  
vs. Drain - Source Voltage

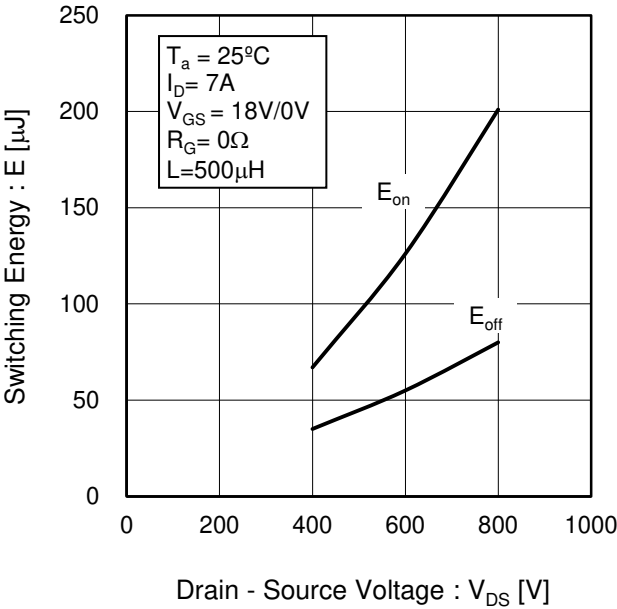


Fig.20 Typical Switching Loss  
vs. Drain Current

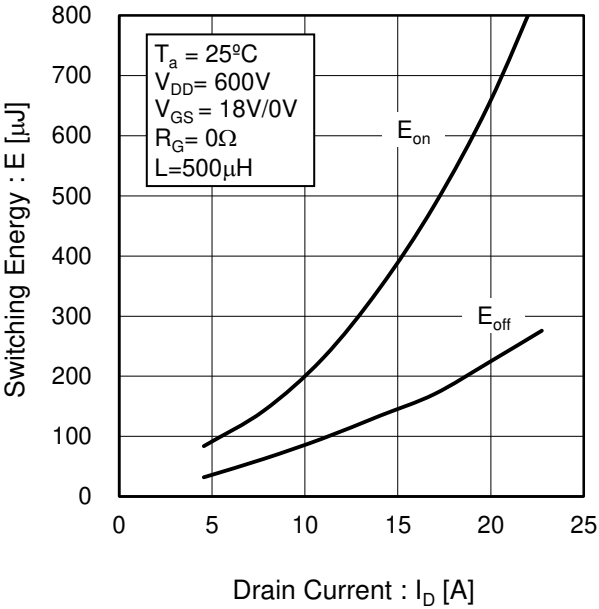
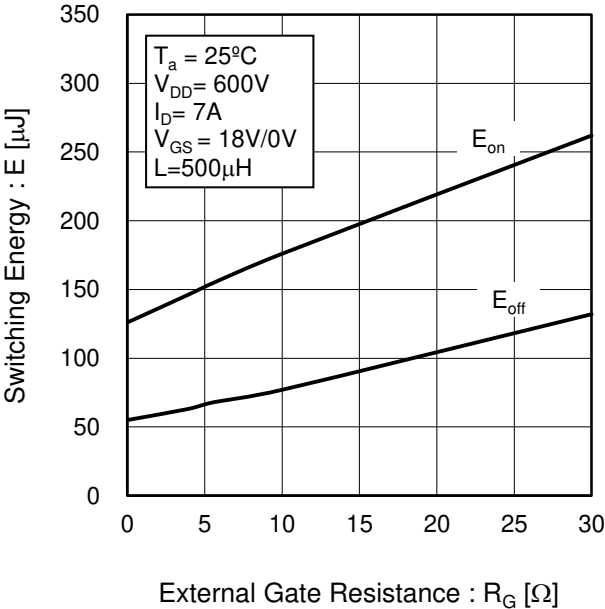


Fig.21 Typical Switching Loss  
vs. External Gate Resistance



●Electrical characteristic curves

Fig.22 Inverse Diode Forward Current vs. Source - Drain Voltage

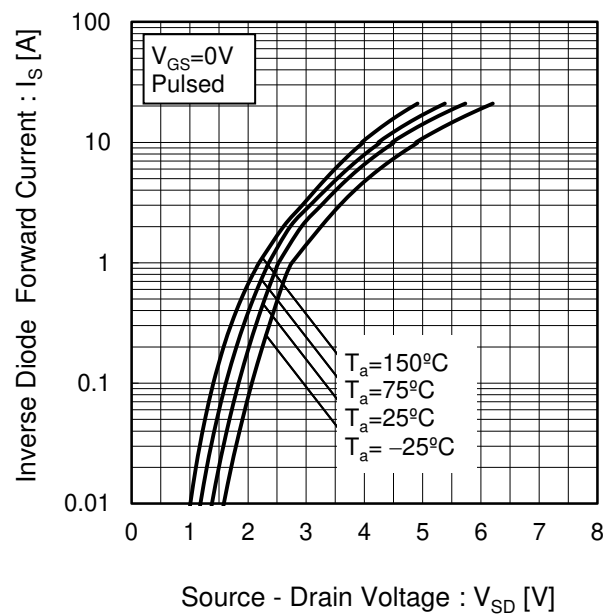
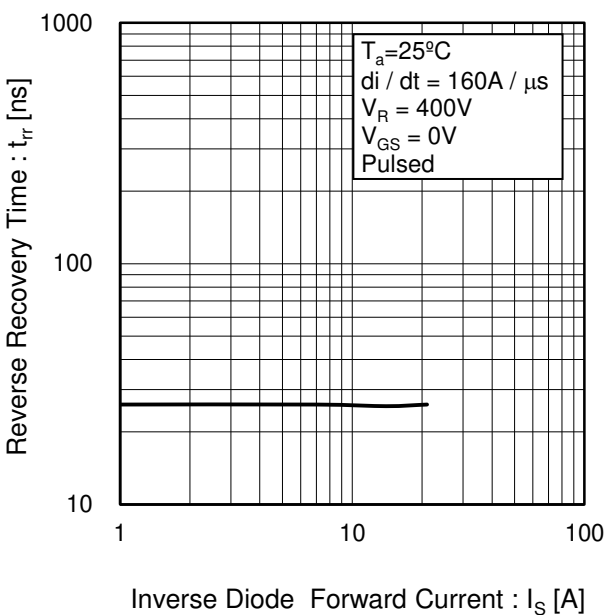


Fig.23 Reverse Recovery Time vs. Inverse Diode Forward Current



●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

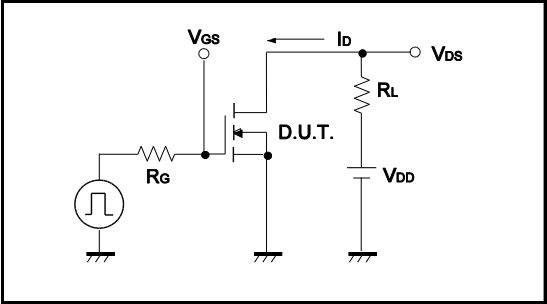


Fig.1-2 Switching Waveforms

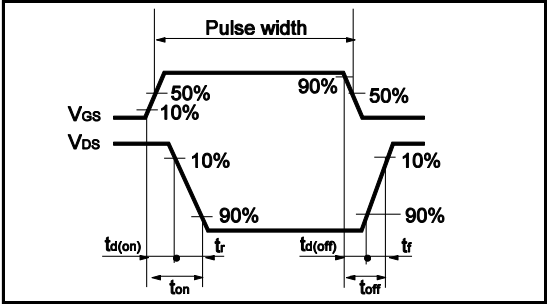


Fig.2-1 Gate Charge Measurement Circuit

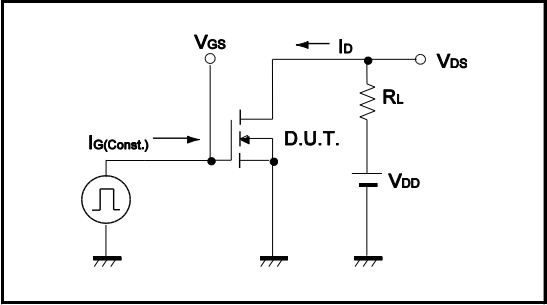


Fig.2-2 Gate Charge Waveform

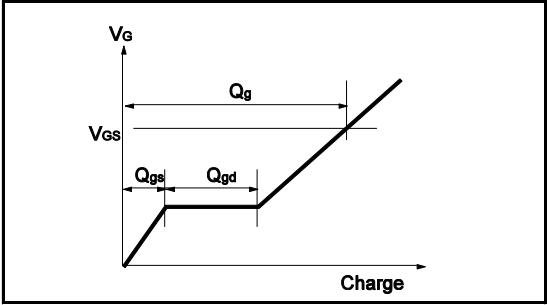


Fig.3-1 Switching Energy Measurement Circuit

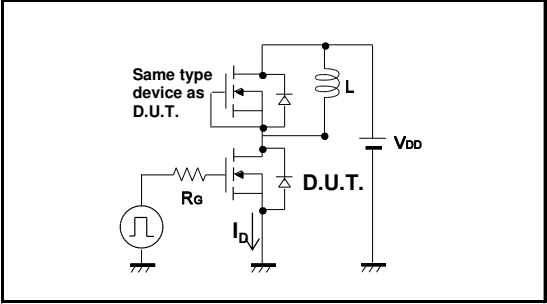


Fig.3-2 Switching Waveforms

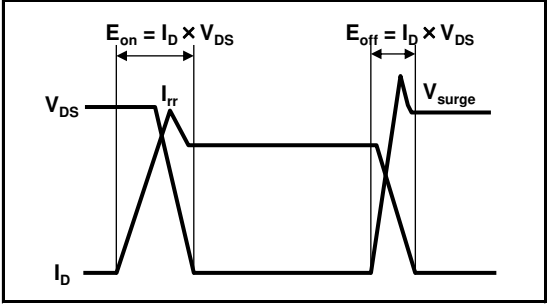


Fig.4-1 Reverse Recovery Time Measurement Circuit

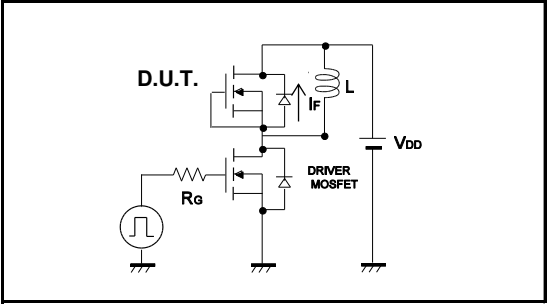
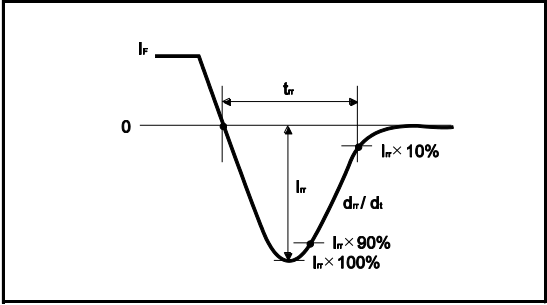
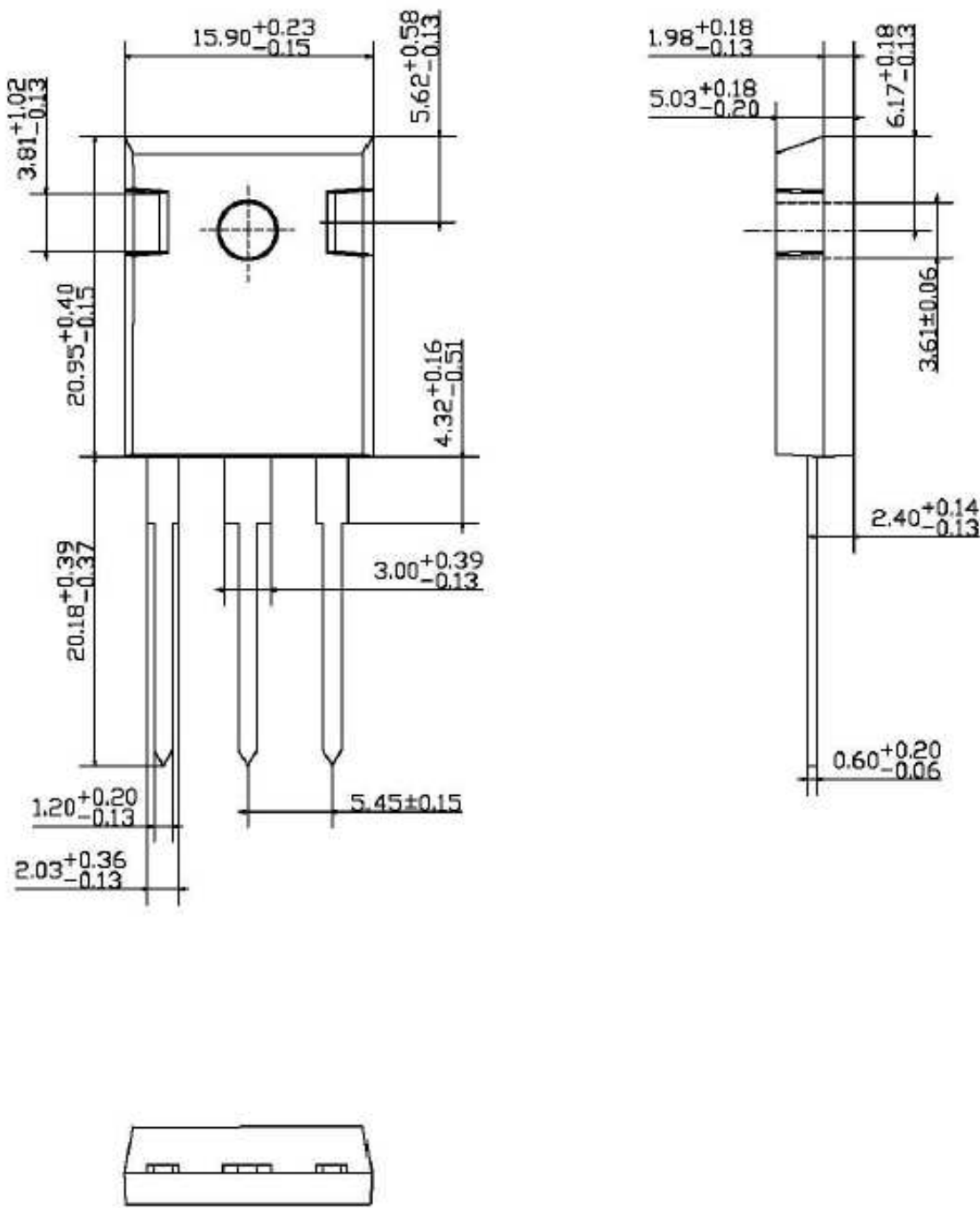


Fig.4-2 Reverse Recovery Waveform



●Dimensions (Unit : mm)

TO-247





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